

PCN Number:	20140523000			PCN Date:	05/27/2014						
Title:	Qualification of Reduced Wire Bond diameter for the Family of Discrete Clip & Power Block Devices										
Customer Contact:	PCN Manager	Phone:	+1(214)480-6037	Dept:	Quality Services						
Proposed 1st Ship Date:	08/27/2014	Estimated Sample Availability:	Date provided upon request								
Change Type:											
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Assembly Process	<input checked="" type="checkbox"/>	Assembly Materials						
<input type="checkbox"/>	Design	<input type="checkbox"/>	Electrical Specification	<input type="checkbox"/>	Mechanical Specification						
<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process						
<input type="checkbox"/>	Wafer Bump Site	<input type="checkbox"/>	Wafer Bump Material	<input type="checkbox"/>	Wafer Bump Process						
<input type="checkbox"/>	Wafer Fab Site	<input type="checkbox"/>	Wafer Fab Materials	<input type="checkbox"/>	Wafer Fab Process						
	<input type="checkbox"/>	Part number change									
PCN Details											
Description of Change:											
Texas Instruments is pleased to announce the qualification a reduced bond wire diameter for the family of Discrete Clip & Power Block Devices:											
<table border="1"> <thead> <tr> <th></th> <th>Current</th> <th>New</th> </tr> </thead> <tbody> <tr> <td>Bond Wire/Diameter</td> <td>Au, 2.0 mil</td> <td>Au, 1.0 mil</td> </tr> </tbody> </table>							Current	New	Bond Wire/Diameter	Au, 2.0 mil	Au, 1.0 mil
	Current	New									
Bond Wire/Diameter	Au, 2.0 mil	Au, 1.0 mil									
Reason for Change:											
Continuity of Supply											
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):											
None											
Changes to product identification resulting from this PCN:											
None											
Product Affected											
CSD16321Q5	CSD16414Q5	CSD17570Q5B	CSD58869Q5D								
CSD16322Q5	CSD16415Q5	CSD17573Q5B	CSD58870Q5D								
CSD16323Q3	CSD16515Q5	CSD17575Q3	CSD86330Q3D								
CSD16325Q5	CSD16556Q5B	CSD17576Q5B	CSD86350Q5D								
CSD16327Q3	CSD16570Q5B	CSD17590Q5B	CSD86360Q5D								
CSD16340Q3	CSD17303Q5	CSD18502Q5B	CSD87330Q3D								
CSD16341Q5	CSD17304Q3	CSD18509Q5B	CSD87331Q3D								
CSD16350Q5	CSD17308Q3	CSD18532NQ5B	CSD87333Q3D								
CSD16401Q5	CSD17309Q3	CSD18532Q5B	CSD87350Q5D								
CSD16406Q3	CSD17311Q5	CSD18540Q5B	CSD87351Q5D								
CSD16407Q5	CSD17312Q5	CSD19502Q5B	CSD87351ZQ5D								
CSD16408Q5	CSD17556Q5B	CSD19532Q5B	CSD87352Q5D								
CSD16409Q3	CSD17559Q5	CSD58865Q5D	CSD87353Q5D								
CSD16411Q3	CSD17566Q3	CSD58867Q3D									

Qualification Data – Approved May, 2014

This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.

Reference Qualification# 1 : CSD87331Q3D (MSL 1-260C)

Package Construction Details

Assembly Site:	PAC	Mold Compound:	SID#200805
# Pins-Designator, Family:	8-DQZ, LSON-CLIP	Mount Solder:	SID#200757
Lead frame (Finish, Base):	Matte Sn, Cu	Bond Wire:	1.0 Mil Dia., Au

Qualification: Plan Test Results

Reliability Test	Conditions	Sample Size/Fail
**T/C -40C/125C	-40C/+125C (500 Cyc)	77/0

Notes **- Preconditioning sequence: Level 1-260C.

Qualification Data – Approved May, 2014

This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.

Reference Qualification# 2 : CSD58869Q5D (MSL 1-260C)

Package Construction Details

Assembly Site:	PAC	Mold Compound:	SID#202828
# Pins-Designator, Family:	8-DQY, LSON-CLIP	Mount Solder:	SID#200757
Lead frame (Finish, Base):	Matte Sn, Cu	Bond Wire:	1.0 Mil Dia., Au

Qualification: Plan Test Results

Reliability Test	Conditions	Sample Size/Fail
**T/C -40C/125C	-40C/+125C (500 Cyc)	77/0

Notes **- Preconditioning sequence: Level 1-260C.

Qualification Data – Approved May, 2014

This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.

Reference Qualification# 3 : CSD16407Q5 (MSL 1-260C)

Package Construction Details

Assembly Site:	PAC	Mold Compound:	SID#202828
# Pins-Designator, Family:	8-DQH, LSON-CLIP	Mount Solder:	SID#200757
Lead frame (Finish, Base):	Matte Sn, Cu	Bond Wire:	1.0 Mil Dia., Au

Qualification: Plan Test Results

Reliability Test	Conditions	Sample Size/Fail
**T/C -40C/125C	-40C/+125C (500 Cyc)	77/0

Notes **- Preconditioning sequence: Level 1-260C.

Qualification Data – Approved May, 2014

This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.

Reference Qualification# 4 : CSD25401Q3 (MSL 1-260C)

Package Construction Details

Assembly Site:	PAC	Mold Compound:	SID#202828
# Pins-Designator, Family:	8-DQG, LSON-CLIP	Mount Solder:	SID#200757
Lead frame (Finish, Base):	Matte Sn, Cu	Bond Wire:	1.0 Mil Dia., Au
Qualification: <input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results			
Reliability Test	Conditions	Sample Size/Fail	
**T/C -40C/125C	-40C/+125C (500 Cyc)	77/0	
Notes **- Preconditioning sequence: Level 1-260C.			

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com